
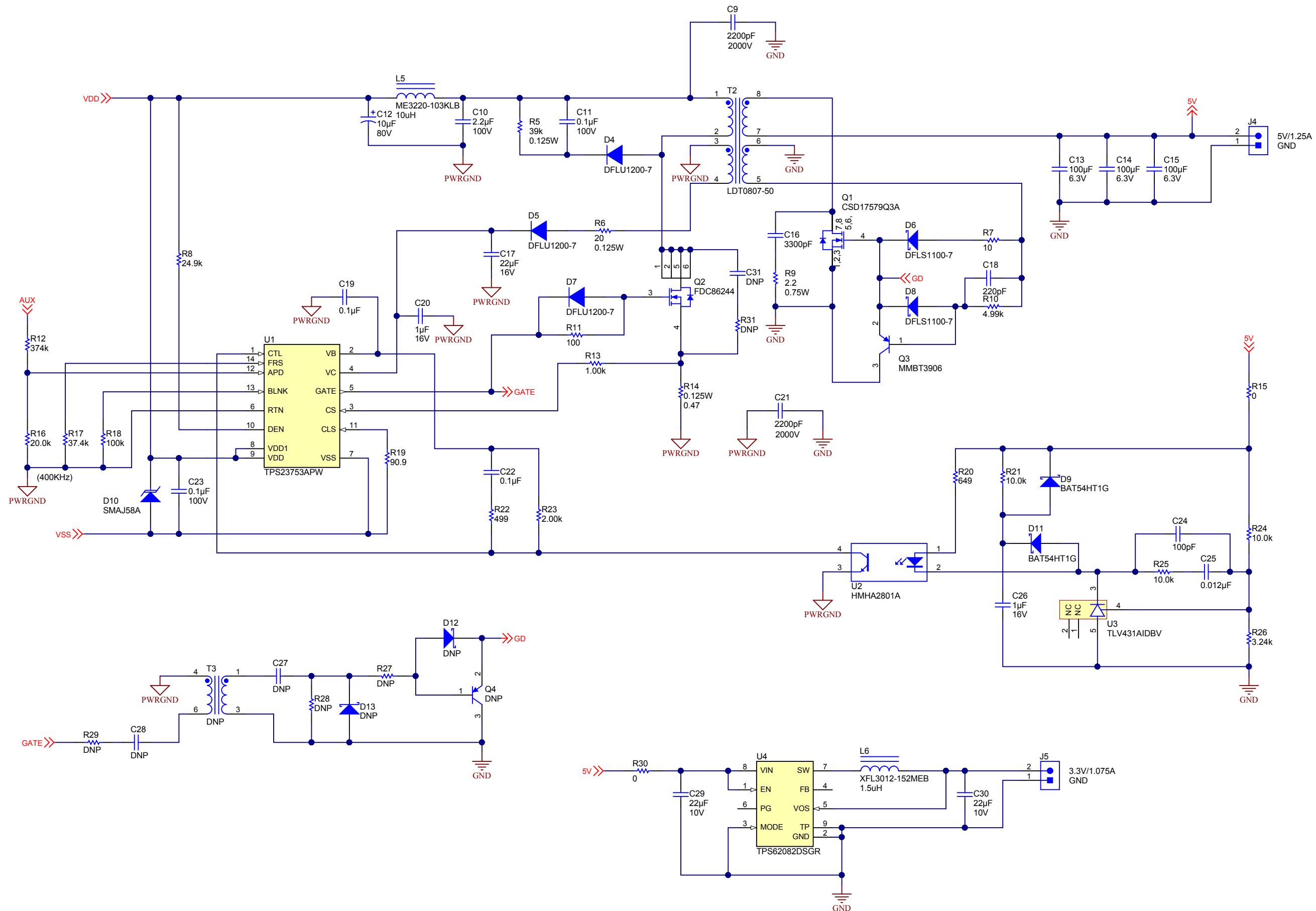


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Orderable: N/A	Designed for: Public Release	Mod. Date: 8/11/2015
TID #: N/A	Project Title: Small, High Efficiency Class 3 PoE Converter	
Number: PMP11271	Rev: B	Sheet Title: PoE/AUX Input
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By: D Strasser	File: PMP11271_RevB_SH1.SchDoc	Size: B
Engineer: D Strasser	Contact: N/A	


  
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Orderable: N/A	Designed for: Public Release	Mod. Date: 8/11/2015
TID #: N/A	Project Title: Small, High Efficiency Class 3 PoE Converter	
Number: PMP11271	Rev: B	Sheet Title: Isolated Synchronous Flyback Converter
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By: D Strasser	File: PMP11271_RevB_SH2.SchDoc	Size: B
Engineer: D Strasser	Contact: N/A	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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